

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	9	("5796163" "6201305" "6586676" "624504").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 16:09
S2	6859	@ad<="20031230" and (257/668).ccls. or (257/737-738).ccls. or (257/780-781).ccls. or (257/E21.503).ccls. or (257/E23.119).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:34
S3	5226	@ad<="20031230" and (257/734).ccls. or (257/784).ccls. or (257/779).ccls. or (257/786).ccls. or (257/792).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 12:17
S4	1	@ad<="20031230" and (257/668).ccls. and 'solder contact' same 'pad' same 'flexible'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 14:24
S5	1	@ad<="20031230" and (257/668).ccls. and 'bonding pad' same 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 13:37
S6	44	@ad<="20031230" and (257/668).ccls. and 'bonding pad' same 'flexible'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 13:41
S7	3	@ad<="20031230" and (257/668).ccls. and 'bonding pad' same 'compliant layer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 08:57
S8	1	"6147401".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:45
S9	1	"6043563".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:47
S10	1	"5885849".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:48
S11	1	"4736236".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:52
S12	1	"4670770".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:52
S13	1	"4612566".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:53
S14	1	"4527330".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:53

EAST Search History

S15	1	"4413308".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:53
S16	1	"4232512".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:54
S17	1	"4215359".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:56
S18	1	"4200975".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:56
S19	4	@ad<="20031230" and (257/668). ccls. and 'bonding pad' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:05
S20	1	"6147401".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:58
S21	1	"6043563".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:58
S22	1	"5929517".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:58
S23	1	"5885849".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:59
S24	1	"5749997".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:59
S25	1	"5679977".PN.	USPAT; USOCR	OR	ON	2005/02/03 14:00
S26	1	"5666270".PN.	USPAT; USOCR	OR	ON	2005/02/03 14:01
S27	1	"5180311".PN.	USPAT; USOCR	OR	ON	2005/02/03 14:02
S28	1	@ad<="20031230" and (257/668). ccls. and 'bonding pad' same 'Resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:08
S29	3	@ad<="20031230" and (257/668). ccls. and 'pad' same 'compliance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:09
S30	111	@ad<="20031230" and 'bonding pad' same 'Resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:09
S31	12	@ad<="20031230" and 'bonding pad' same 'Resilience'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:09

EAST Search History

S33	30	@ad<="20031230" and (257/668).ccls. and 'pad' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:04
S34	44	@ad<="20031230" and 'bonding pad' same 'compliance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:10
S35	136	@ad<="20031230" and 'bonding pad' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:10
S36	3	@ad<="20031230" and 'solder contact' same 'pad' same 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:11
S37	919	@ad<="20031230" and 'pad' with 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 17:12
S38	11	@ad<="20031230" and 'solder' and 'pad' with 'different' with 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:13
S39	3685	@ad<="20031230" and (257/668).ccls. or (257/737-738).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:34
S40	1	"6049130".PN.	USPAT; USOCR	OR	ON	2005/02/03 14:35
S41	1	"6034431".PN.	USPAT; USOCR	OR	ON	2005/02/03 14:36
S42	570	@ad<="20031230" and 'compliant contact'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:05
S43	74	@ad<="20031230" and 'solder ball' and 'compliant contact'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:05
S44	1	"6333563".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:18
S45	1	"6221697".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:19

EAST Search History

S46	1	"6443351".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:22
S47	1	"6409073".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:23
S48	1	"6396156".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:23
S49	1	"6369451".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:24
S50	1	"6333104".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:24
S51	20	@ad<="20031230" and 'bonding pad' with 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:44
S53	219	@ad<="20031230" and 'bonding pad' and 'solder ball' and 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:45
S54	81	@ad<="20031230" and 'bonding pad' and 'solder ball' and 'compliant layer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:45
S55	11	("6333559") or ("6376279") or ("6541844") or ("6465867") or ("6204165").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 08:49
S56	2	("6211572").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 08:49
S57	1	"5874782".PN.	USPAT; USOCR	OR	ON	2005/02/04 08:50
S58	1	"5777379".PN.	USPAT; USOCR	OR	ON	2005/02/04 08:52
S59	1	"5679977".PN.	USPAT; USOCR	OR	ON	2005/02/04 08:57
S61	233	@ad<="20031230" and 'compliant' with 'packaging'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 08:58
S62	92	@ad<="20031230" and 'bonding pad' and 'compliant' with 'package'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 08:59

EAST Search History

S63	2	@ad<="20031230" and 'bonding pad' same 'compliant' with 'packaging'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 08:59
S64	1	"5001302".PN.	USPAT; USOCR	OR	ON	2005/06/17 14:23
S69	1	"5777379".PN.	USPAT; USOCR	OR	ON	2005/06/17 14:36
S70	1	"5677576".PN.	USPAT; USOCR	OR	ON	2005/06/17 14:36
S73	1	"6333565".PN.	USPAT; USOCR	OR	ON	2005/06/17 15:18
S74	1	"6277669".PN.	USPAT; USOCR	OR	ON	2005/06/17 15:21
S75	117	@ad<="20031230" and 'solder ball' same 'contact pad' same 'flexible'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 16:04
S76	570	@ad<="20031230" and 'solder ball' and 'contact pad' and 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:23
S77	607	@ad<="20031230" and 'contact pad' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:23
S78	1289	@ad<="20031230" and 'contact pad' same 'resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:23
S79	13	@ad<="20031230" and 'solder ball' with 'contact pad' same 'resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:43
S80	18	@ad<="20031230" and 'solder ball' with 'contact pad' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:45
S81	1543	@ad<="20031230" and 'pad' same 'contact' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:24

EAST Search History

S82	8	@ad<="20031230" and 'solder ball' same 'contact pad' with 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:25
S83	77	@ad<="20031230" and 'solder ball' and 'contact pad' with 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 16:18
S84	1	"5956235".PN.	USPAT; USOCR	OR	ON	2005/06/17 15:32
S85	1	"5868304".PN.	USPAT; USOCR	OR	ON	2005/06/17 15:32
S86	81	@ad<="20031230" and 'solder ball' and 'contact pad' with 'resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:43
S87	8	@ad<="20031230" and 'solder ball' same 'contact pad' with 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:45
S89	739	@ad<="20031230" and 'contact pad' with 'resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 16:05
S90	302	@ad<="20031230" and 'contact pad' with 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 16:12
S91	57	@ad<="20031230" and 'bonding pad' with 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 16:12
S92	58	@ad<="20031230" and 'bonding pad' with 'resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 16:12
S93	576	@ad<="20031230" and 'bonding pad' with 'flexible'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 16:12
S94	1	"6147401".PN.	USPAT; USOCR	OR	ON	2005/06/17 16:14
S95	1	"6043563".PN.	USPAT; USOCR	OR	ON	2005/06/17 16:14

EAST Search History

S97	1086	@ad<="20031230" and 'compliant' and 'solder balls' and 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 08:37
S99	70	@ad<="20031230" and 'compliant' and 'solder balls' and 'copper' and 'TCE'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 17:22
S100	1	"6503777".PN.	USPAT; USOCR	OR	ON	2005/06/27 08:41
S101	1	"6394819".PN.	USPAT; USOCR	OR	ON	2005/06/27 08:41
S102	6	(("5943597") or ("6028364") or ("6394819")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/17 16:10
S103	3	("6806570").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/17 16:15
S104	1	"6503777".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:15
S105	1	"6394819".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:15
S106	1	"6064576".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:16
S107	1	"6028364".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:16
S108	1	"5602422".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:16
S109	2	("6720212").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/17 16:17
S110	9	@ad<="20031230" and 'solder ball' same 'contact pad' with 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 16:21
S111	41	@ad<="20031230" and 'contact pad' with 'compliant layer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 16:21

EAST Search History

S11 2	184	@ad<="20031230" and 'pad' with 'compliant layer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 16:22
S11 3	302	@ad<="20031230" and 'pad' with 'compliant material'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 08:12
S11 4	74	@ad<="20031230" and 'solder' and 'pad' with 'compliant material'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 16:44
S11 5	1	"6743660".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:28
S11 6	1	"6433427".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:28
S11 7	1	"6235552".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:30
S11 8	1	"6277669".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:31
S11 9	1	"6197613".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:32
S12 0	1	"6187680".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:33
S12 1	1	"6187615".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:33
S12 2	1	"6163463".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:34
S12 3	1	"6235552".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:34
S12 4	1	"6071755".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:34
S12 5	1	"5851911".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:35
S12 6	1	"5969424".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:35
S12 7	1	"6033939".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:36
S12 8	1	"6037044".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:36
S12 9	210	@ad<="20031230" and 'solder' and 'bonding pad' with 'stress'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 16:44

EAST Search History

S13 0	71	@ad<="20031230" and 'solder' same 'bonding pad' with 'stress'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 16:54
S13 1	30	@ad<="20031230" and 'solder' same 'bonding pad' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 17:32
S13 2	1	"6838368".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:55
S13 3	1	"6809020".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:55
S13 4	1	"6413845".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:56
S13 5	1	"6125043".PN.	USPAT; USOCR	OR	ON	2005/10/17 16:56
S13 6	72	@ad<="20031230" and 'compliant' and 'solder balls' and 'copper' and 'TCE'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 17:00
S13 7	1	"20020089058".PN.	US-PGPUB	OR	ON	2005/10/17 17:02
S13 8	1	"6638870".PN.	USPAT; USOCR	OR	ON	2005/10/17 17:02
S13 9	1	"6337445".PN.	USPAT; USOCR	OR	ON	2005/10/17 17:03
S14 0	1	"6147401".PN.	USPAT; USOCR	OR	ON	2005/10/17 17:04
S14 1	22	@ad<="20031230" and 'bonding pad' with 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 17:12
S14 2	28	@ad<="20031230" and 'bond pad' with 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 17:12
S14 3	191	@ad<="20031230" and 'stress buffer' and ('ball' or 'bump') and 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 17:23
S14 4	38	@ad<="20031230" and 'stress buffer' and ('ball' or 'bump') and 'pad' and 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 13:54

EAST Search History

S14 5	1	"6743660".PN.	USPAT; USOCR	OR	ON	2005/10/17 17:29
S14 6	1	"6433427".PN.	USPAT; USOCR	OR	ON	2005/10/17 17:30
S14 7	1	"6277669".PN.	USPAT; USOCR	OR	ON	2005/10/17 17:30
S14 8	1	"6235552".PN.	USPAT; USOCR	OR	ON	2005/10/17 17:30
S14 9	1	"6189208".PN.	USPAT; USOCR	OR	ON	2005/10/17 17:31
S15 0	93	@ad<="20031230" and 'solder ball' and 'compliant pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 08:23
S15 1	20	@ad<="20031230" and 'solder ball' same 'compliant pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 08:13
S15 3	1230	@ad<="20031230" and 'solder ball' and ('compliant' or 'stress') with 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 08:25
S15 4	342	@ad<="20031230" and 'solder ball' and 'compliant' with 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 08:25
S15 5	25	@ad<="20031230" and 'solder ball' and 'compliant' with 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 08:39
S15 6	307	@ad<="20031230" and 'young modulus' with 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 08:45
S15 7	307	@ad<="20031230" and 'copper' with 'young' adj1 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 09:19
S15 8	13	@ad<="20031230" and 'compliant material' same 'polymer' same 'dielectric' same 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 10:12

EAST Search History

S15 9	2	("5148266").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/18 10:12
S16 2	688	@ad<="20031230" and ('stress buffer' or 'compliant') and ('ball' or 'bump') and 'pad' and 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/09 11:48
S16 3	18	(("6806570") or ("6255737") or ("6900548") or ("6624504") or ("6770547") or ("6946723") or ("6835595") or ("6835595")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/18 12:12
S16 4	1	"6284563".PN.	USPAT; USOCR	OR	ON	2006/04/18 13:30
S16 5	1	"6211572".PN.	USPAT; USOCR	OR	ON	2006/04/18 13:30
S16 6	1	"5925931".PN.	USPAT; USOCR	OR	ON	2006/04/18 13:30
S16 7	1	"5874782".PN.	USPAT; USOCR	OR	ON	2006/04/18 13:30
S16 8	1	"5844782".PN.	USPAT; USOCR	OR	ON	2006/04/18 13:31
S16 9	1	"20020076651".PN.	US-PGPUB	OR	ON	2006/04/18 13:35
S17 0	1	"6472724".PN.	USPAT; USOCR	OR	ON	2006/04/18 13:35
S17 1	1	"6472249".PN.	USPAT; USOCR	OR	ON	2006/04/18 13:35
S17 2	1	"6313532".PN.	USPAT; USOCR	OR	ON	2006/04/18 13:35
S17 3	1	"6287893".PN.	USPAT; USOCR	OR	ON	2006/04/18 13:35
S17 4	1	"6037662".PN.	USPAT; USOCR	OR	ON	2006/04/18 13:36
S17 5	1	"5887520".PN.	USPAT; USOCR	OR	ON	2006/04/18 13:36
S17 6	1	"5887520".PN.	USPAT; USOCR	OR	ON	2006/04/18 13:36
S17 8	297	@ad<="20031230" and (stress or strain) with (buffer or relax\$5 or relieve) same (ball or bump) same pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 14:01

EAST Search History

S18 0	350	@ad<="20031230" and (stress or strain) with (buffer or relax\$5 or relieve or compliant) same (ball or bump) same pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 14:42
S18 1	1	"5550407".PN.	USPAT; USOCR	OR	ON	2006/04/18 14:06
S18 2	1	"5834844".PN.	USPAT; USOCR	OR	ON	2006/04/18 14:06
S18 3	1	"5886415".PN.	USPAT; USOCR	OR	ON	2006/04/18 14:06
S18 4	1	"6111311".PN.	USPAT; USOCR	OR	ON	2006/04/18 14:06
S18 5	1	"6111317".PN.	USPAT; USOCR	OR	ON	2006/04/18 14:07
S18 6	1	"6153448".PN.	USPAT; USOCR	OR	ON	2006/04/18 14:07
S18 7	1	"6181010".PN.	USPAT; USOCR	OR	ON	2006/04/18 14:07
S18 8	1	"6181569".PN.	USPAT; USOCR	OR	ON	2006/04/18 14:07
S18 9	1	"6184577".PN.	USPAT; USOCR	OR	ON	2006/04/18 14:09
S19 0	1	"6255737".PN.	USPAT; USOCR	OR	ON	2006/04/18 14:09
S19 1	1	"6313532".PN.	USPAT; USOCR	OR	ON	2006/04/18 14:10
S19 2	1	"6674158".PN.	USPAT; USOCR	OR	ON	2006/04/18 14:10
S19 4	441	@ad<="20031230" and (pad or electrode) with ("stress relaxation" or buffer or "stress relieve" or compliant) same bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 15:11
S19 5	562	@ad<="20031230" and "compliant pad" or "compliant bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 17:28
S19 6	82	@ad<="20031230" and "compliant bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 15:12
S19 7	471	@ad<="20031230" and "compliant pad"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 16:20

EAST Search History

S19 8	39	@ad<="20031230" and "compliant pad" same stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 15:32
S19 9	2	("5508228").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/18 16:20
S20 0	1	"6838368".PN.	USPAT; USOCR	OR	ON	2006/04/18 17:25
S20 1	1	"6809020".PN.	USPAT; USOCR	OR	ON	2006/04/18 17:26
S20 2	1	"6413845".PN.	USPAT; USOCR	OR	ON	2006/04/18 17:27
S20 3	1	"6125043".PN.	USPAT; USOCR	OR	ON	2006/04/18 17:27
S20 4	1	"4372809".PN.	USPAT; USOCR	OR	ON	2006/04/18 17:27
S20 5	598	@ad<="20031230" and "compliant pad" or "compliant bump" or "compliant ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 17:28
S20 6	566	@ad<="20031230" and solder same pad same compliant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 17:43
S20 7	33	@ad<="20031230" and solder same "bonding pad" same compliant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 17:33
S20 8	238	@ad<="20031230" and solder same "bonding pad" same stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 17:33
S20 9	65	@ad<="20031230" and solder same "bonding pad" same buffer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 17:33
S21 0	18	@ad<="20031230" and solder same "bonding pad" same relief	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 17:34

EAST Search History

S21 1	7	@ad<="20031230" and solder same "bonding pad" same relax\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 17:34
S21 2	275	@ad<="20031230" and solder same pad with compliant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/18 17:43